

### 1200V 60A N-Channel SiC MOSFET

#### **Features**

- · Low On-Resistance
- · Low Capacitance
- Avalanche Ruggedness
- Halogen Free, RoHS Compliant

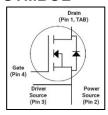
#### **BENEFITS**

- Higher System Efficiency
- Parallel Device Convenience
- High Temperature Application
- High Frequency Operation

## **Application**

- Switch Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Uninterruptible Power Supply (UPS)
- EV Charging station & Motor Drives
- · Solar/ Wind Renewable Energy
- Power Inverters & DC/DC Converters

#### **SYMBOL**





TO-247-4L

### **ASSEMBLY MESSAGE**

Product Name	Package	Packaging
BXW60M1K2J	TO-247-4L	Tube

#### ABSOLUTE MAXIMUM RATINGS (Tc=25°C unless otherwise noted)

Parameter		Symbol	Rating	Unit
			TO-247-4L	
Drain-Source Voltage		$V_{DSS}$	1200	V
Continuous Drain Current	T <sub>C</sub> = 25°C, VGS=18V	ID	60	Α
Single Pulse Avalanche Energy	L=10mH	Eas	460	mJ
	L=10mH	las	9.6	Α
Pulsed Drain Current		I <sub>DM</sub>	240	Α
Recommend Gate Source Voltage(Static)		V <sub>GS</sub> ,op	-3/+18	V
Maximum Gate Source Voltage(AC (f > 1Hz))		V <sub>GS,</sub> max	-5/+22	V
Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	271.7	W
Soldering Temperature		T∟	260	°C
Operating Junction and Storage Temperature Range		T <sub>J</sub> ,T <sub>STG</sub>	150,-55~150	°C
Thermal Resistance, Junction to Case		R <sub>θJC</sub>	0.46	°C/W



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## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub>=25°C,unless otherwise Noted)

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	VGS=0V, ID=250μA	1200			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	VDS=1200V, VGS=0V			10	uA	
Gate-Body Leakage Current, Forward	I <sub>GSS</sub>	VGS=18V,VDS = 0V			250	nA	
ON CHARACTERISTICS							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	VDS=10V, ID=5mA	1.5		3.0	V	
		VGS=20V, ID=30A		36	43		
Drain-Source On-State Resistance		VGS=18V, ID=30A		40	48		
Diam-Source On-State Resistance	R <sub>DS(ON)</sub>	VGS=15V, ID=30A		50	60	mΩ	
		VGS=18V, ID=30A, TJ=150℃		80			
DYNAMIC PARAMETERS							
Input Capacitance	C <sub>ISS</sub>	VD0 4000VVV00 0V		2400		pF	
Output Capacitance	Coss	VDS=1000V,VGS=0V,		120		pF	
Reverse Transfer Capacitance	Crss	f=1MHz,VAC=25mV		18		pF	
SWITCHING PARAMETERS							
Total Gate Charge(Note2)	$Q_{G}$			170		nC	
Gate Source Charge	Q <sub>GS</sub>	VDD =800V,		10		nC	
Gate Drain Charge	Q <sub>GD</sub>	VGS =-3/+18 V, ID=30A		48		nC	
Gate plateau voltage	$V_{pl}$			2.6		V	
Turn-ON Delay Time	t <sub>D(ON)</sub>			45		ns	
Turn-ON Rise Time	t <sub>R</sub>	VDS=800V, ID=30A,		119		ns	
Turn-OFF Delay Time	t <sub>D(OFF)</sub>	VGS = -3/+18 V ,RG=25Ω		123		ns	
Turn-OFF Fall-Time	t <sub>F</sub>			145		ns	
Internal Gate Resistance	R <sub>G(int.)</sub>	f =1MHz, VAC=25mV		2.4		Ω	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	IS=30A, VGS=-3V		4.6		V	
Continuous Diode Forward Current	Is	VGS = -3V		60		Α	
Reverse Recovery Time	t <sub>rr</sub>	VGS = -3/+18V,IF = 60A,		62		ns	
Reverse Recovery Charge	Qrr	VDS=400V,		298		nC	
Peak Reverse Recovery Current	I <sub>rrm</sub>	di/dt =500A /µs		10		Α	



#### **TYPICAL CHARACTERISTICS**

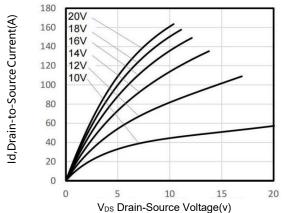


Figure 1. Typical Output Characteristics

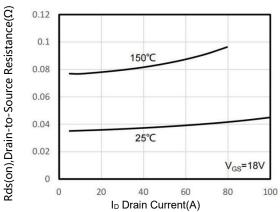


Figure 3. On-Resistance versus Drain Current

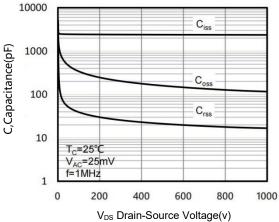
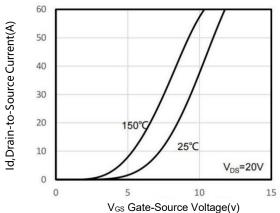


Figure 5. Typical Capacitance versus V<sub>DS</sub>



**Figure 2. Typical Transfer Characteristics** 

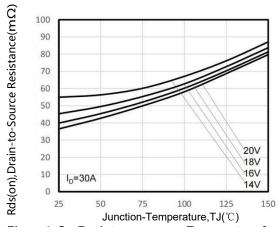


Figure 4. On-Resistance versus Temperature for Various Gate Voltage

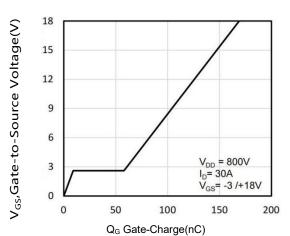


Figure 6. Typical Gate Charge versus V<sub>GS</sub>

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## **TYPICAL CHARACTERISTICS(Cont.)**

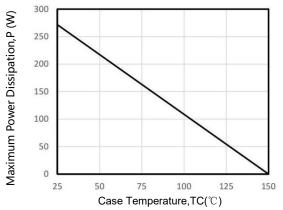
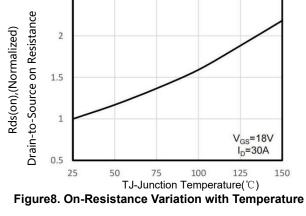


Figure 7. Maximum Power Dissipation Derating versus Case Temperature



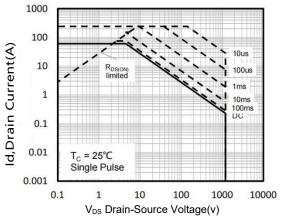


Figure9. Maximum Safe Operating Area

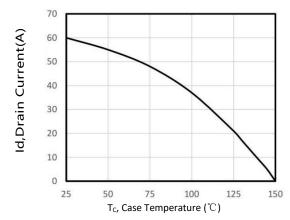
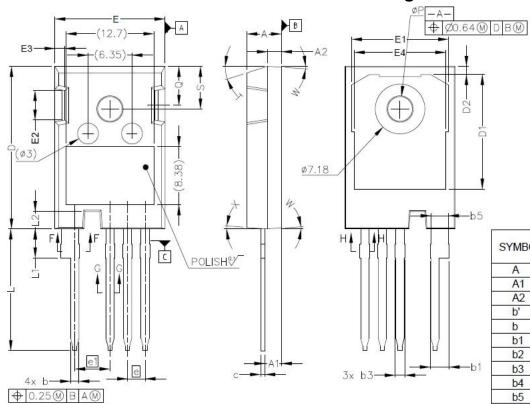


Figure 10. Maximum Continuous Drain Current versus Case Temperature

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# TO-247-4L Package



CVMPOL	MILLIMETERS		
SYMBOL	MIN	MAX	
Α	4.83	5.21	
A1	2.29	2.54	
A2	1.91	2.16	
b'	1.07	1.28	
b	1.07	1.33	
b1	2.39	2.94	
b2	2.39	2.84	
b3	1.07	1.60	
b4	1.07	1.50	
b5	2.39	2.69	
b6	2.39	2.64	
c'	0.55	0.65	
С	0.55	0.68	
D	23.30	23.60	
D1	16.25	17.65	
D2	0.95	1.25	
E	15.75	16.13	
E1	13.10	14.15	
E2	3.68	5.10	
E3	1.00	1.90	
E4	12.38	13.43	
е	2.54 BSC		
e1	5.08 BSC		
N	4		
L	17.31	17.82	
L1	3.97	4.37	
L2	2.35	2.65	
øΡ	3.51	3.65	
Q	5.49	6.00	
S	6.04	6.30	
T	17.5° I	REF.	
W	3.5 ° REF.		
X	4°	REF.	

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	b',b2,b4,b6
BASE METAL	i i
i V	
<u> </u>	
PLATING	<b>→</b> b,b1,b3,b5

## **Revision history**

## **Document revision history**

Date	Revision	Changes
22-Jan-2022	1.0	First release



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